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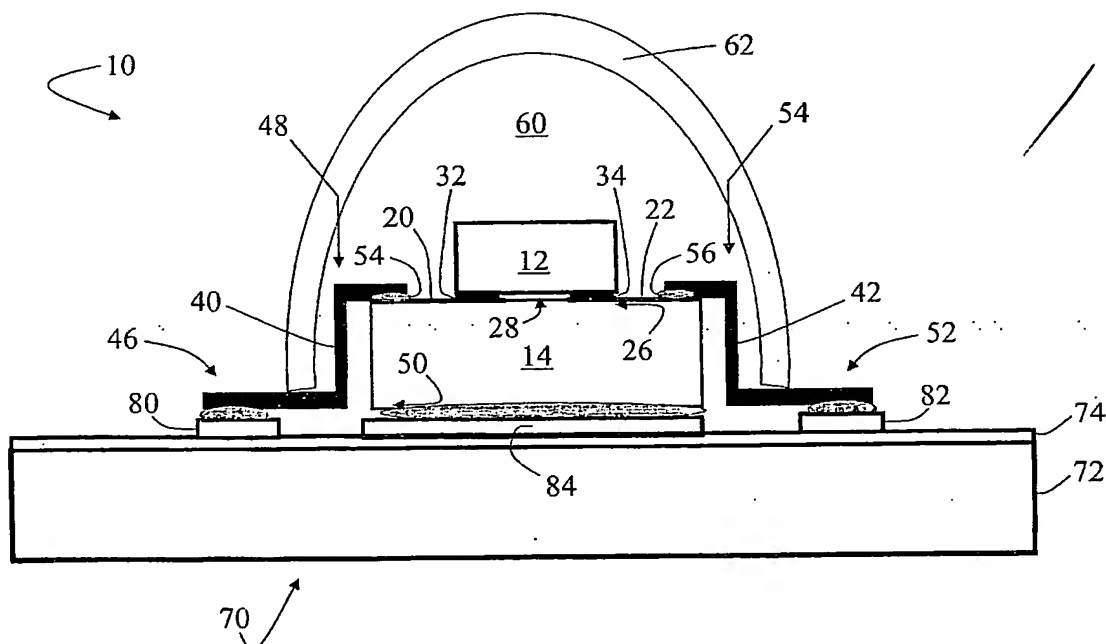
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(54) Title: SURFACE MOUNT LIGHT EMITTING CHIP PACKAGE



(57) Abstract: A surface mount light emitting package includes a chip carrier having top and bottom principal surfaces. At least one light emitting chip is attached to the top principal surface of the chip carrier. A lead frame attached to the top principal surface of the chip carrier. When surface mounted to an associated support, the bottom principal surface of the chip carrier is in thermal contact with the associated support without the lead frame intervening therebetween.

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